

## SECTION II—CLAIMS

- 1.-13. (Canceled)
14. (Previously Presented) A process of forming a micro electromechanical (MEMS) package comprising:
  - providing a semiconductor device including an active surface;
  - providing a conveyance with at least one embedded MEMS device disposed therein; and
  - disposing the conveyance over the semiconductor device, wherein the at least one embedded MEMS device communicates electrically to the semiconductor device.
15. (Original) The process according to claim 14, wherein the at least one embedded MEMS device is selected from a switch, a capacitor, an inductor, an oscillator, a power supply, and combinations thereof.
16. (Original) The process according to claim 14, wherein the conveyance comprises a via disposed therein, the process further comprising:
  - providing at least one detached MEMS device in a first structure; and
  - accommodating the at least one detached MEMS device through the via, upon the active surface.
17. (Original) The process according to claim 14, wherein the conveyance comprises a via disposed therein, the process further comprising:
  - providing at least one detached MEMS device in a first structure;
  - placing the at least one detached MEMS device on the semiconductor device; and
  - accommodating the at least one detached MEMS device through the via, upon the active surface.
18. (Original) The process according to claim 14, wherein the conveyance comprises a via disposed therein, the process further comprising:
  - providing at least one detached MEMS device in a first structure;

accommodating the at least one detached MEMS device upon the active surface;  
providing a sealing structure; and  
disposing the sealing structure in a manner sufficient to isolate at least one of the  
at least one detached MEMS device.

19. (Original) The process according to claim 14 further comprising:

forming an integrated package comprising the semiconductor device and the  
conveyance.

20. (Original) The process according to claim 14 further comprising:

forming an integrated package comprising the semiconductor device, the  
conveyance, and at least one detached MEMS device in a first structure, wherein the at  
least one detached MEMS device is accommodated upon the semiconductor device.

21. (Original) The process according to claim 20 further comprising:

encapsulating the detached MEMS device and the conveyance to form an  
integrated package.

22. (Original) The process according to claim 14 further comprising:

encapsulating the semiconductor device to form an integrated package, wherein  
the at least one detached MEMS device is accommodated upon the semiconductor  
device.

23. (Original) A process comprising:

providing a semiconductor device;

accommodating a detached micro electromechanical structure (MEMS) device  
upon the semiconductor device;

providing a conveyance over the semiconductor device and around the detached  
MEMS device; and

contacting encapsulation material with at least one of the semiconductor device,  
the detached MEMS device, and the conveyance to form an integrated MEMS package.

24. (Original) The process according to claim 23, further comprising:  
embedding a MEMS device in the conveyance.
25. (Original) The process according to claim 23, further comprising:  
providing a sealing structure; and  
interposing the sealing structure upon the semiconductor device in a manner sufficient to isolate at least one of the at least one detached MEMS device.

26.-30. (Canceled)